

ABSTRACT OF THE DISCLOSURE

An object of the present invention is to provide a semiconductor device including a fuse that can easily be blown by a laser beam and free from a problem of oxidation proceeding from a laser-beam blown portion.

5 In order to accomplish this object, a semiconductor device formed on a substrate includes an interconnection line formed on the substrate and provided to structure a prescribed circuit and a fuse that is incorporated into the interconnection line and can be blown by a laser beam. The fuse and a
10 connection portion electrically connected to the fuse at the interconnection line are formed from different metal materials.